



SAW components

SAW filter

Band 40 partial Post PA

Series/type:	B9635
Ordering code:	B39232B9635P810
Date:	April 25, 2016
Version:	2.0

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SAW filter	2335 MHz

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1 Application

- Low-loss RF filter for smallcells
- Usable pass band 70MHz

2 Features

- Package size 1.4±0.1 mm × 1.1±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

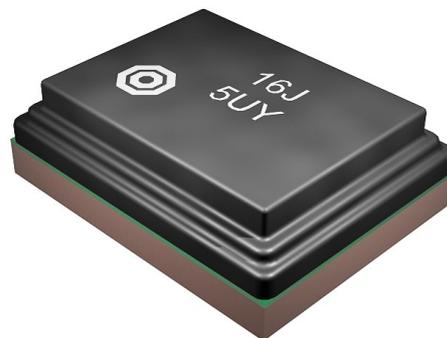
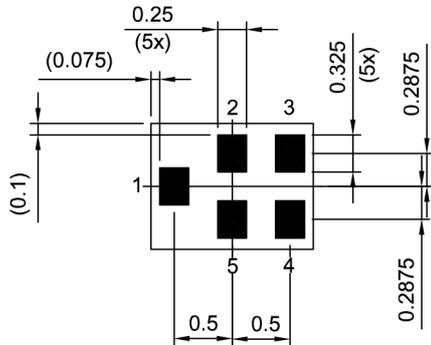


Figure 1: Picture of component with example of product marking.

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3 Package

BOTTOM VIEW



Pad and pitch tolerance ±0.05

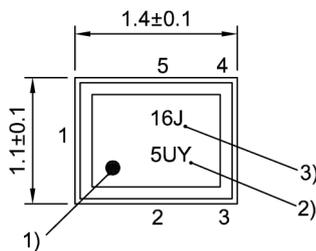
4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW

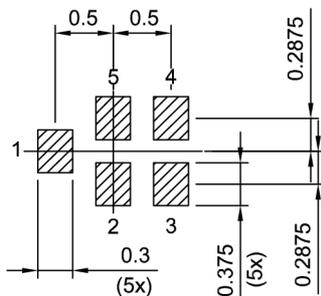


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 17).

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5 Matching circuit

■ $L_{p1} = 9.1 \text{ nH}$

■ $L_{p4} = 8.7 \text{ nH}$

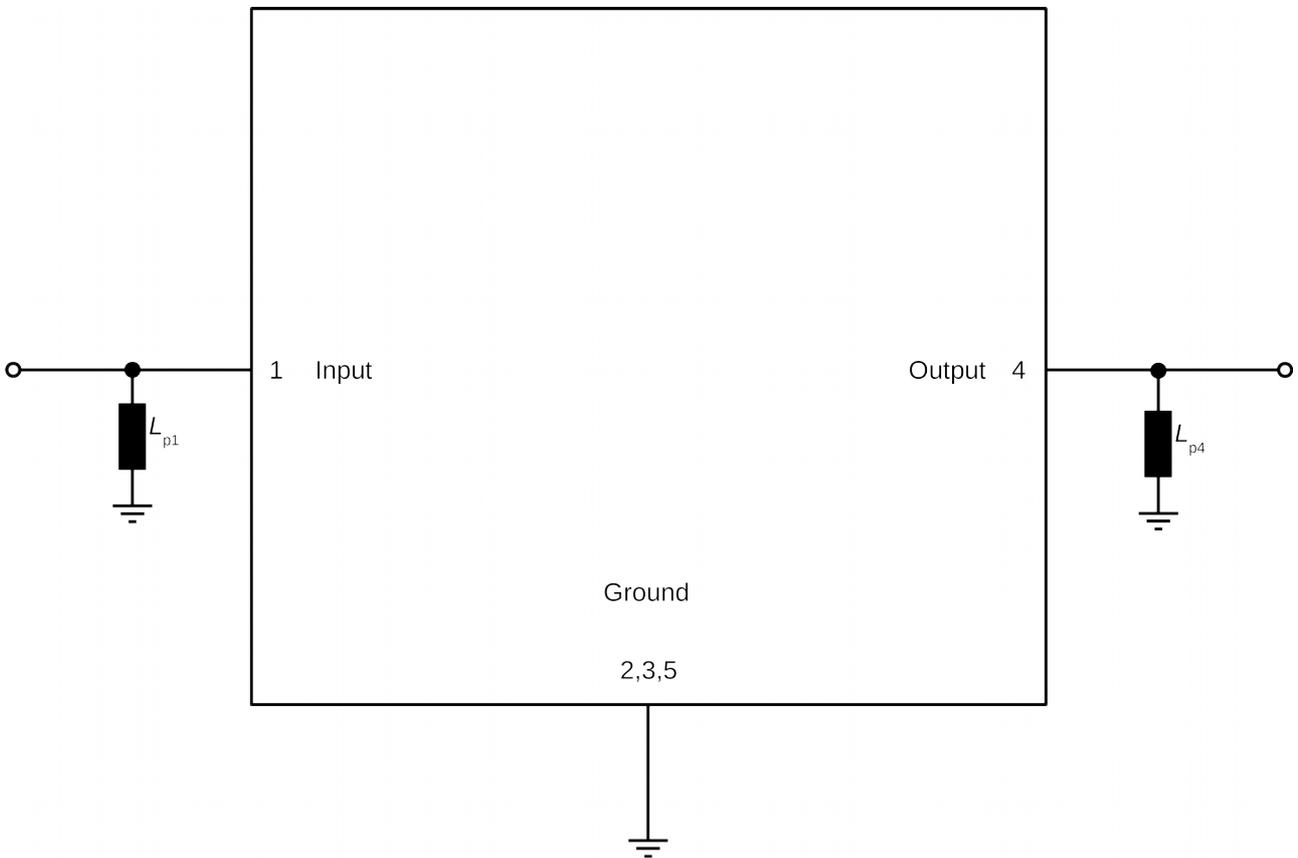


Figure 3: Schematic of matching circuit.

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6 Characteristics

Temperature range for specification

$$T_{\text{SPEC}} = -10\text{ °C} \dots +85\text{ °C}$$

Input terminating impedance

$$Z_{\text{IN}} = 50\ \Omega \text{ with par. } 9.1\ \text{nH}^{(1)}$$

Output terminating impedance

$$Z_{\text{OUT}} = 50\ \Omega \text{ with par. } 8.7\ \text{nH}^{(1)}$$

Characteristics ²⁾			min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
Center frequency		f_{C}	—	2335	—	MHz
Maximum insertion attenuation	2300... 2370	MHz	α_{max}	1.9	2.8	dB
Amplitude ripple (p-p)	2300... 2370	MHz	$\Delta\alpha$	0.9	1.8	dB
	2300... 2370	MHz	$\Delta\alpha^{(3)}$	0.4	1.2	dB
Maximum VSWR			VSWR _{max}			
@ input port	2300... 2370	MHz		1.6	2.0	
@ output port	2300... 2370	MHz		1.8	2.1	
Maximum error vector magnitude	2302.4... 2367.6	MHz	EVM _{max} ⁴⁾	1.3	3.0	%
Minimum attenuation			α_{min}			
	50... 1574	MHz		29	32	dB
	1574... 1577	MHz		29	34	dB
	1577... 1710	MHz		29	34	dB
	1710... 1805	MHz		30	36	dB
	1805... 1845	MHz		33	38	dB
	1845... 1880	MHz		33	39	dB
	1920... 2110	MHz		35	41	dB
	2110... 2170	MHz		33	39	dB
	2170... 2200	MHz		33	38	dB
	2200... 2215	MHz		33	37	dB
	2395... 2400	MHz		10	39	dB
	2400... 2410	MHz		30	42	dB
	2410... 2420	MHz		40	49	dB
	2420... 2440	MHz		43	50	dB
	2440... 2460	MHz		43	51	dB
	2460... 2480	MHz		43	49	dB
	2480... 2490	MHz		43	48	dB
	2490... 2500	MHz		43	48	dB
	2500... 2570	MHz		40	45	dB
	2570... 2620	MHz		40	45	dB
	2620... 2690	MHz		40	45	dB
	2690... 3750	MHz		32	37	dB
	3750... 4600	MHz		25	32	dB

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Characteristics ²⁾	min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
4600... 4800 MHz	25	32	—	dB
4800... 5150 MHz	20	30	—	dB
5150... 5850 MHz	20	28	—	dB
5850... 6000 MHz	20	28	—	dB

- ¹⁾ See Sec. Matching circuit (p. 5).
- ²⁾ T is the ambient temperature of the PCB at component position. Specified min./max. Values are valid for an input power of up to 15dBm.
- ³⁾ Over any channel with band width of 5 MHz.
- ⁴⁾ Error Vector Magnitude (EVM) based on definition given in 3GPP TS 25.141.

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7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$V_{DC} = 0\text{ V}$	
ESD voltage	$V_{ESD}^{1)} = 50\text{ V}$	Machine model.
Input power	P_{IN}	
@ input port: 2300 ... 2370 MHz	25.5 dBm ²⁾	LTE 5MHz downlink for 100000 h @ 55 °C.
Operating lifetime with output power at antenna		
@ 2300 ... 2370 MHz	t.b.d. dBm ³⁾	Continuous wave for 100000 h @ 55 °C.

¹⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

²⁾ Time to failure (TTF) according to accelerated power durability test and wear out models.

³⁾ According to accelerated High Temperature Operating Life (HTOL) test.

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8 Transmission coefficient

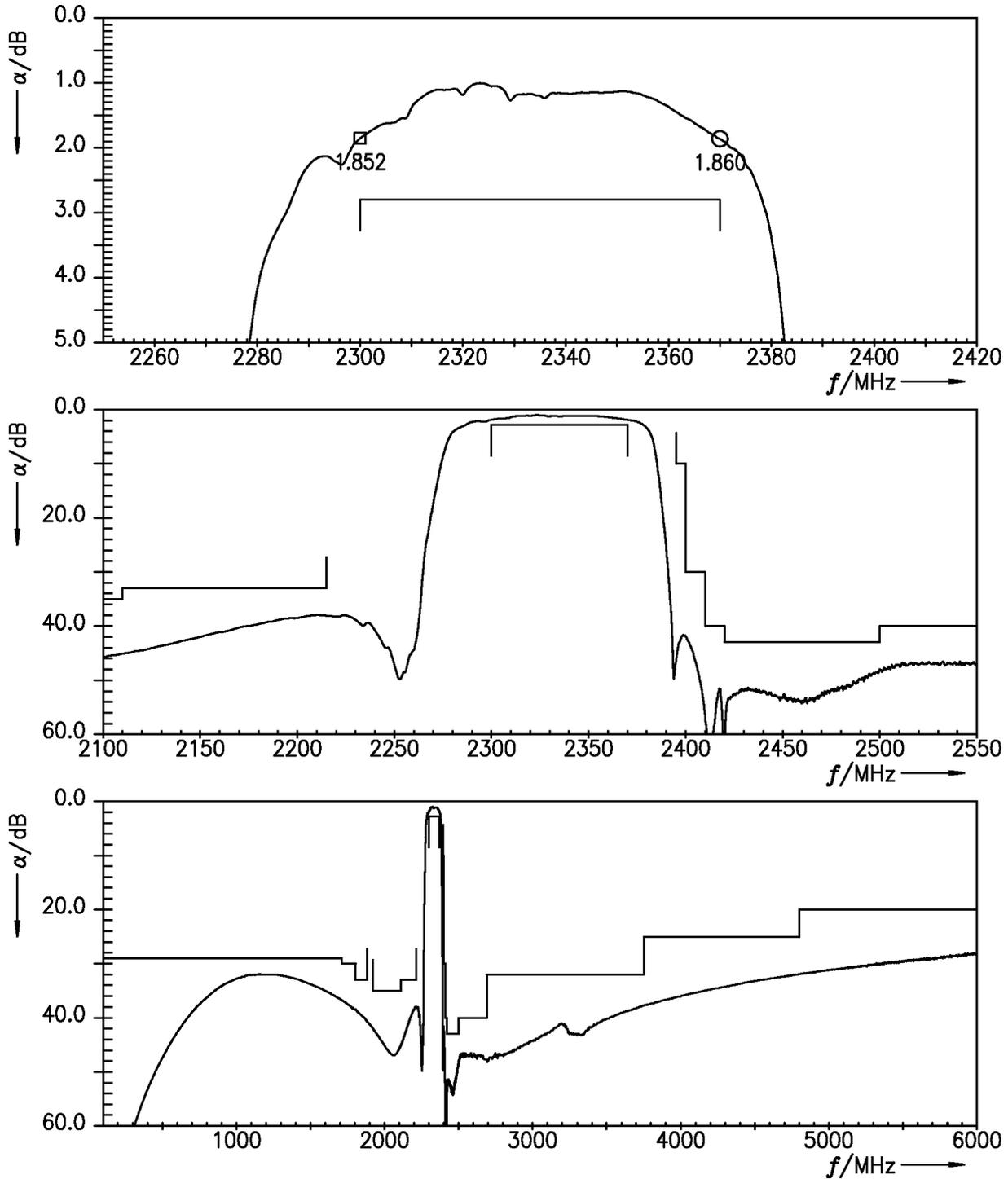


Figure 4: Attenuation.

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9 Reflection coefficients

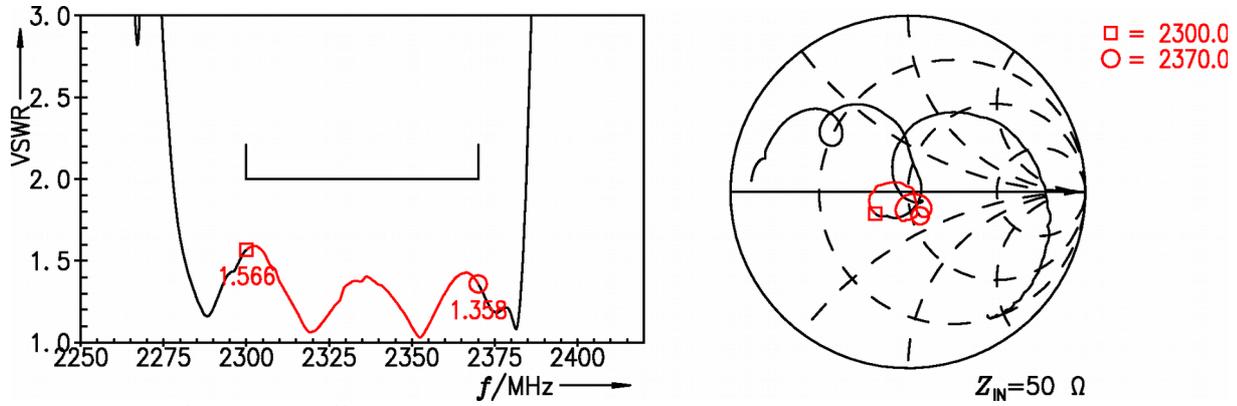


Figure 5: Reflection coefficient at IN port.

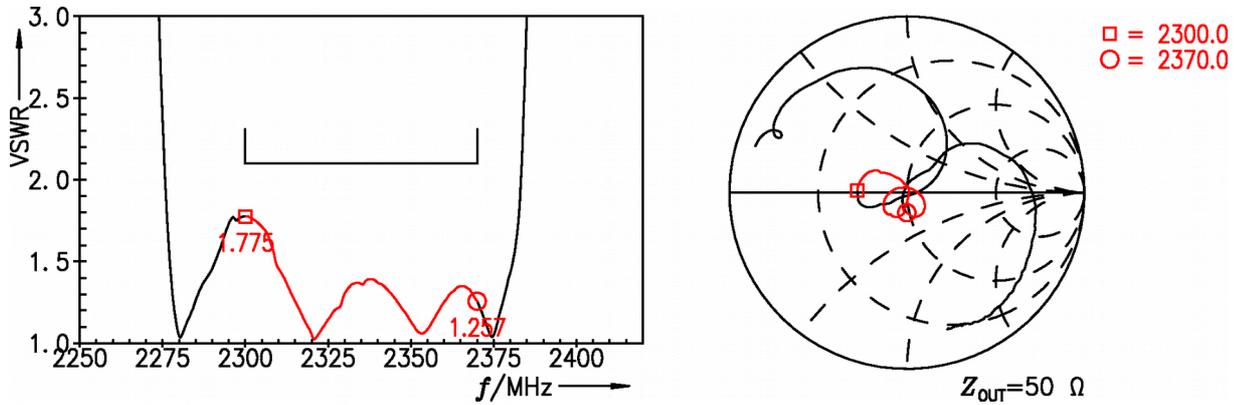


Figure 6: Reflection coefficient at OUT port.

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10 EVM

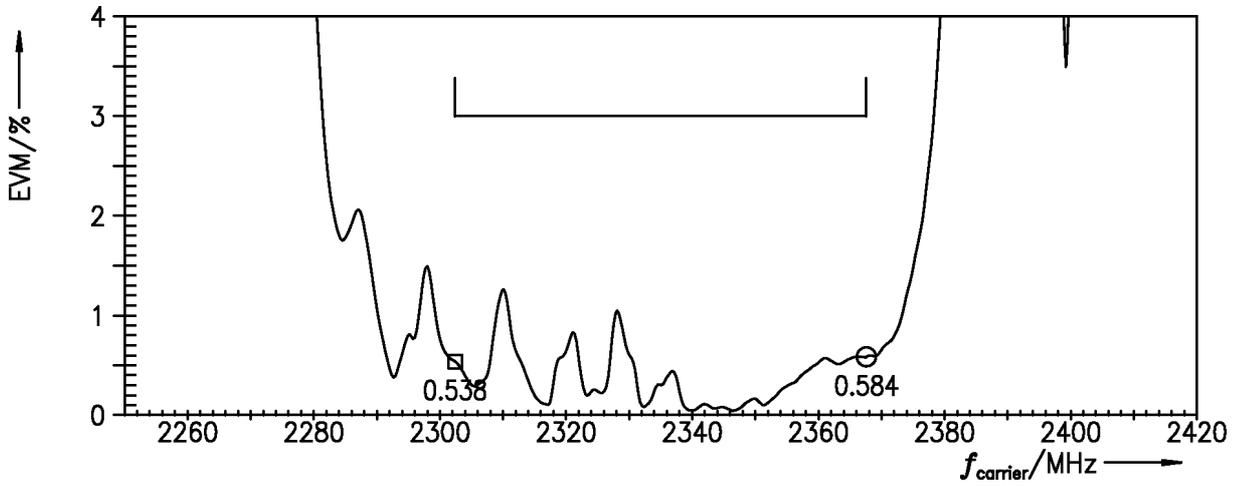


Figure 7: Error vector magnitude.

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11 Packing material

11.1 Tape

Section Y-Y

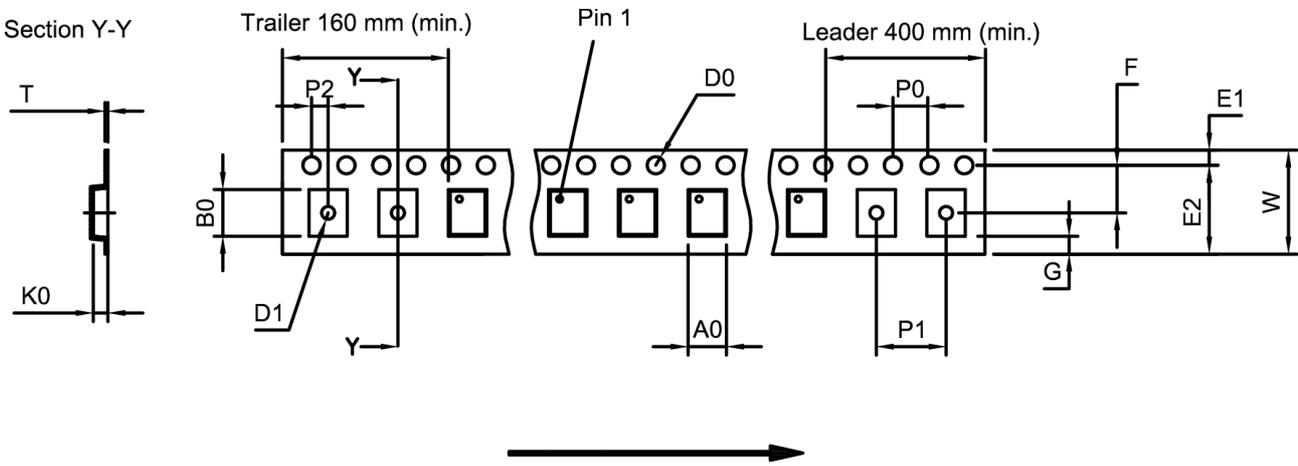


Figure 8: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	1.27±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	1.57±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	0.5±0.1 mm	K ₀	0.62±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

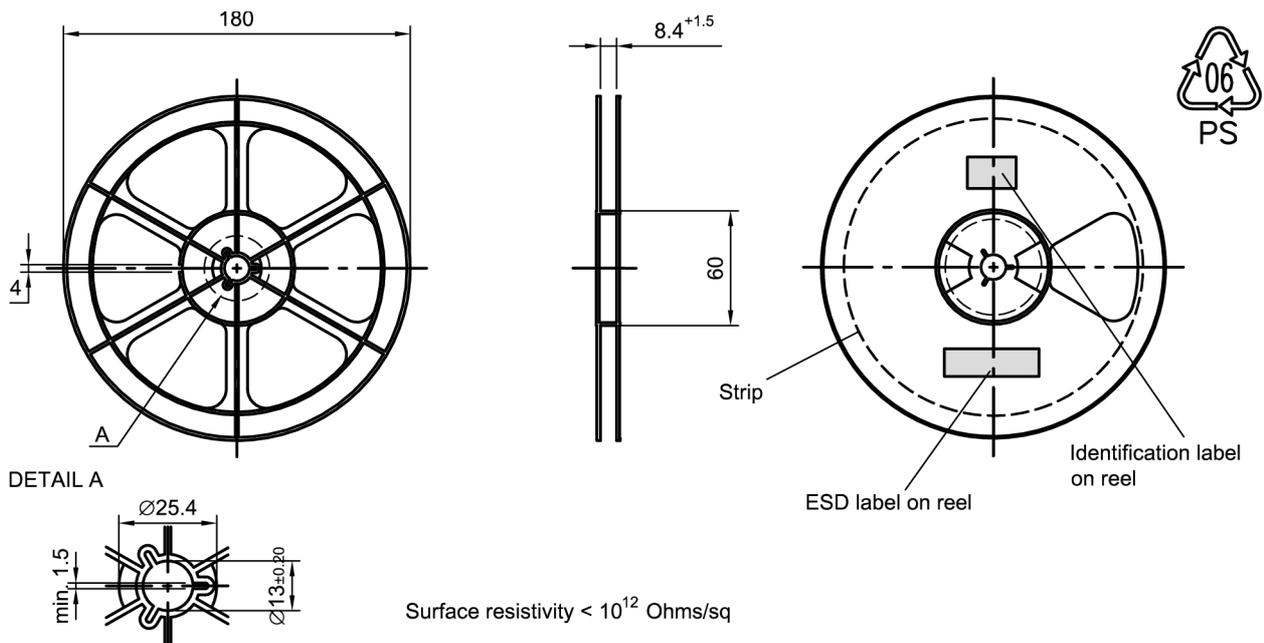


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

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Dimensions [mm]
 X = 220±5
 Y = 235±5
 Sealing area 10±3

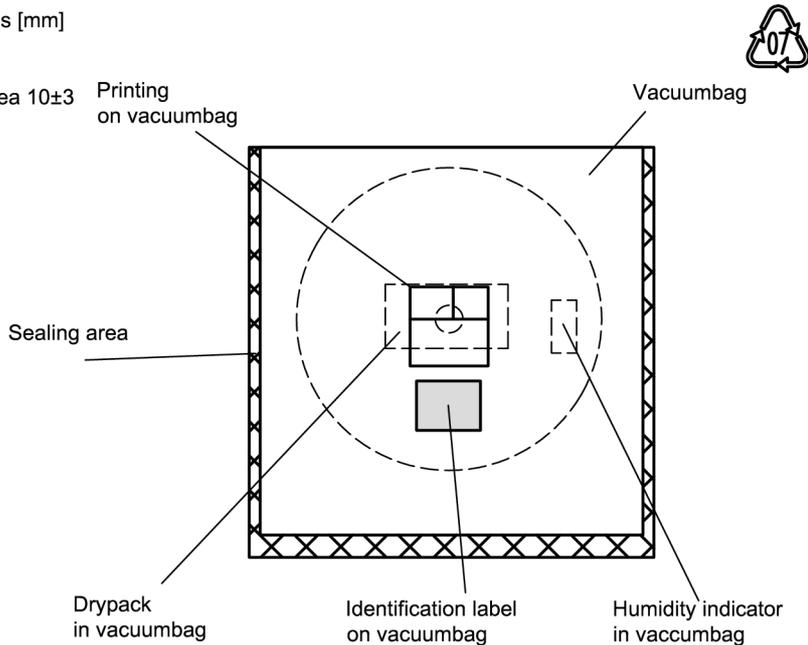


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Dimensions [mm]
 L = 188
 B = 188
 H = 30
 Tolerance ±5

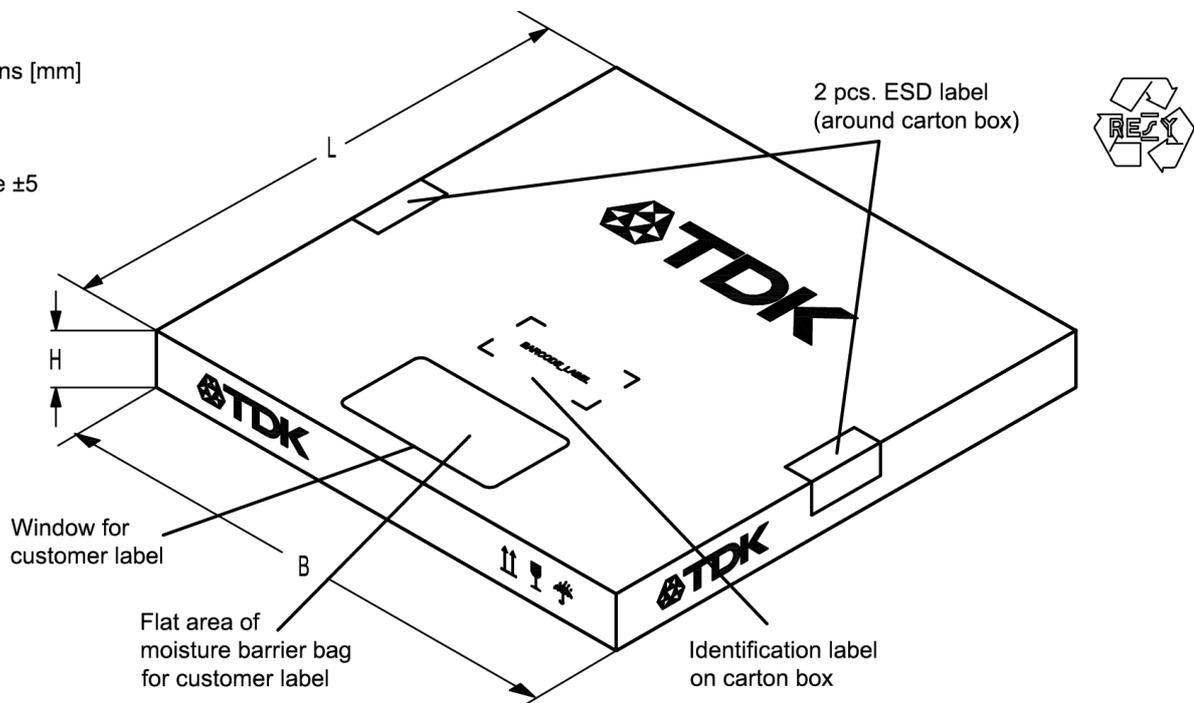


Figure 11: Drawing of folding box for reel with diameter of 180 mm.

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12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

$$\begin{array}{rcl} \mathbf{16J} & \Rightarrow & \mathbf{1234} \\ \mathbf{1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0} & = & \mathbf{1234} \end{array}$$

The BASE32 code for product type B9635 is 9D3.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

$$\begin{array}{rcl} \mathbf{5UY} & \Rightarrow & \mathbf{12345} \\ \mathbf{5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0} & = & \mathbf{12345} \end{array}$$

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

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13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220\text{ °C}$	30 s to 70 s
$T > 230\text{ °C}$	min. 10 s
$T > 245\text{ °C}$	max. 20 s
$T \geq 255\text{ °C}$	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

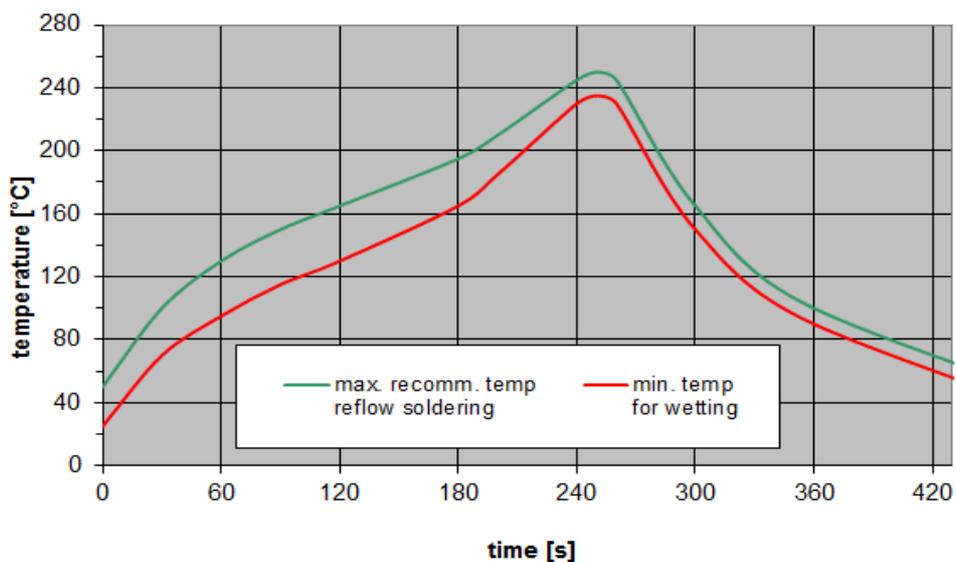


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

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14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

14.4 Ordering codes and packing units

Ordering code	Packing unit
B39232B9635P810	5000 pcs

Table 4: Ordering codes and packing units.

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15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.
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